Principles of Micro- and Nanofabrication for Electronic and Photonic Devices

Film Deposition
Part V: PVD

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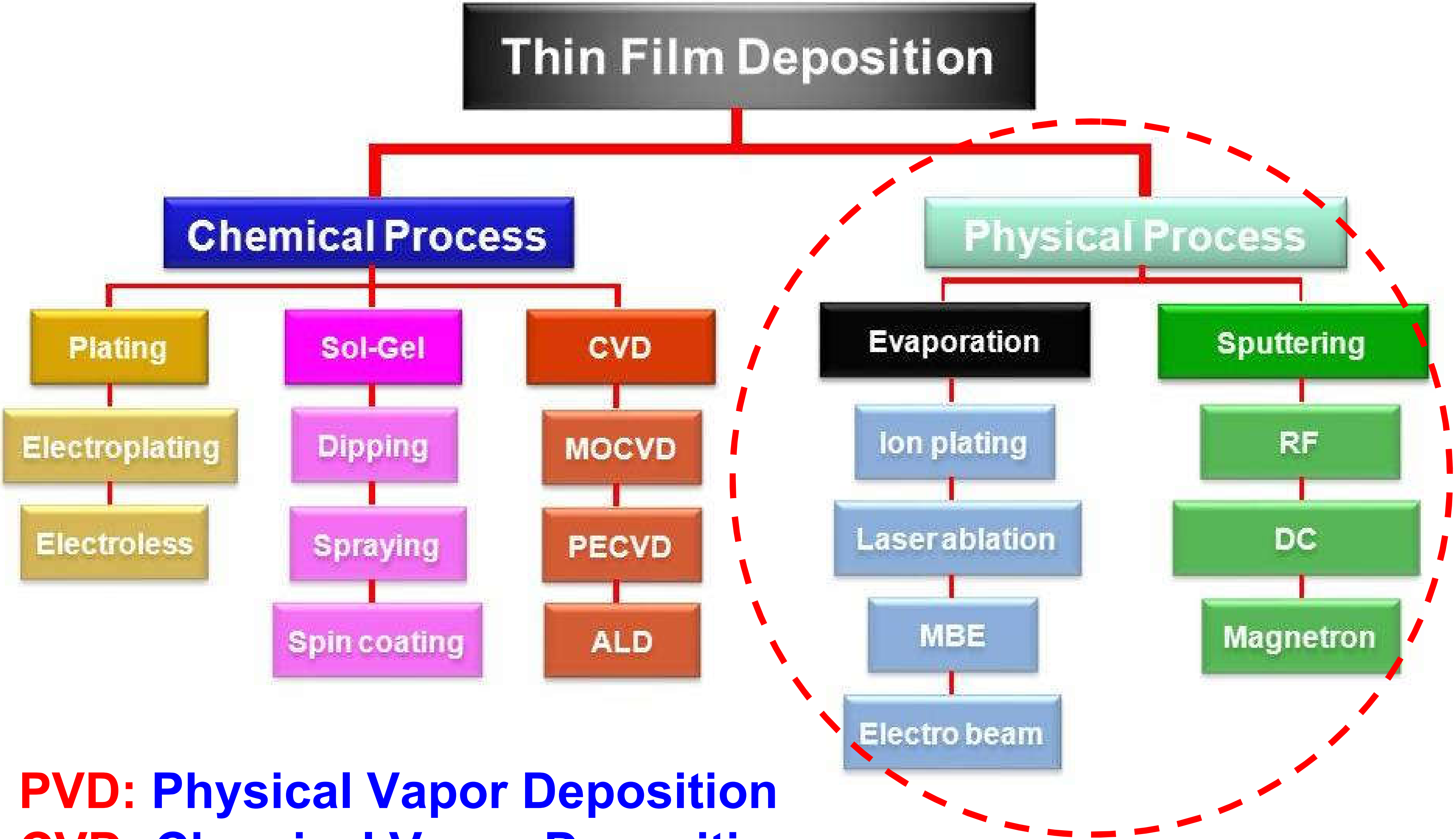
Film Deposition

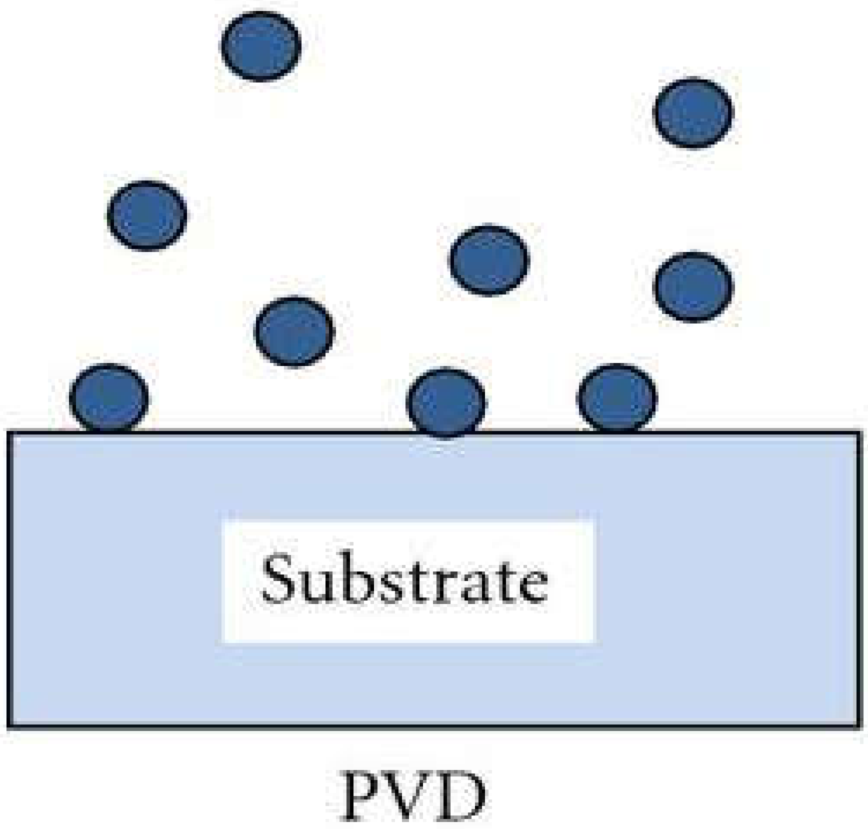


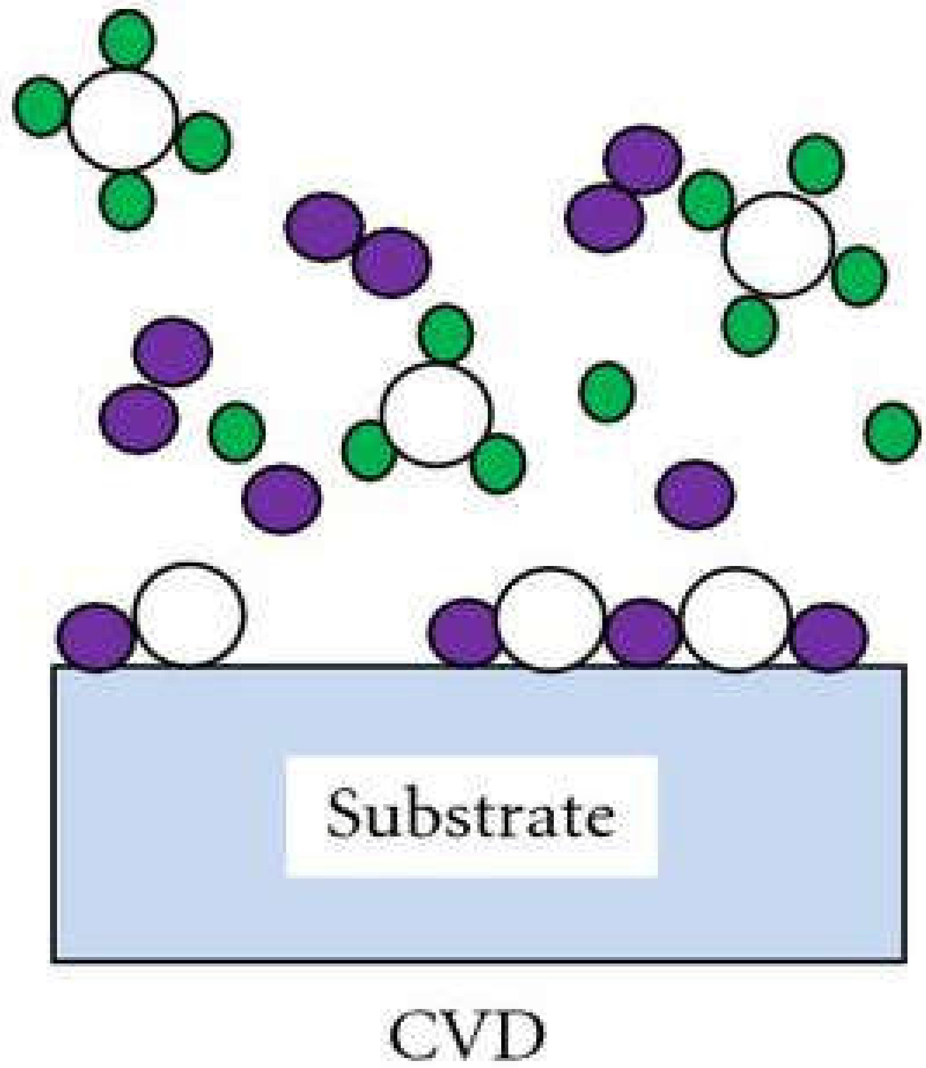
PVD: Physical Vapor Deposition

CVD: Chemical Vapor Deposition

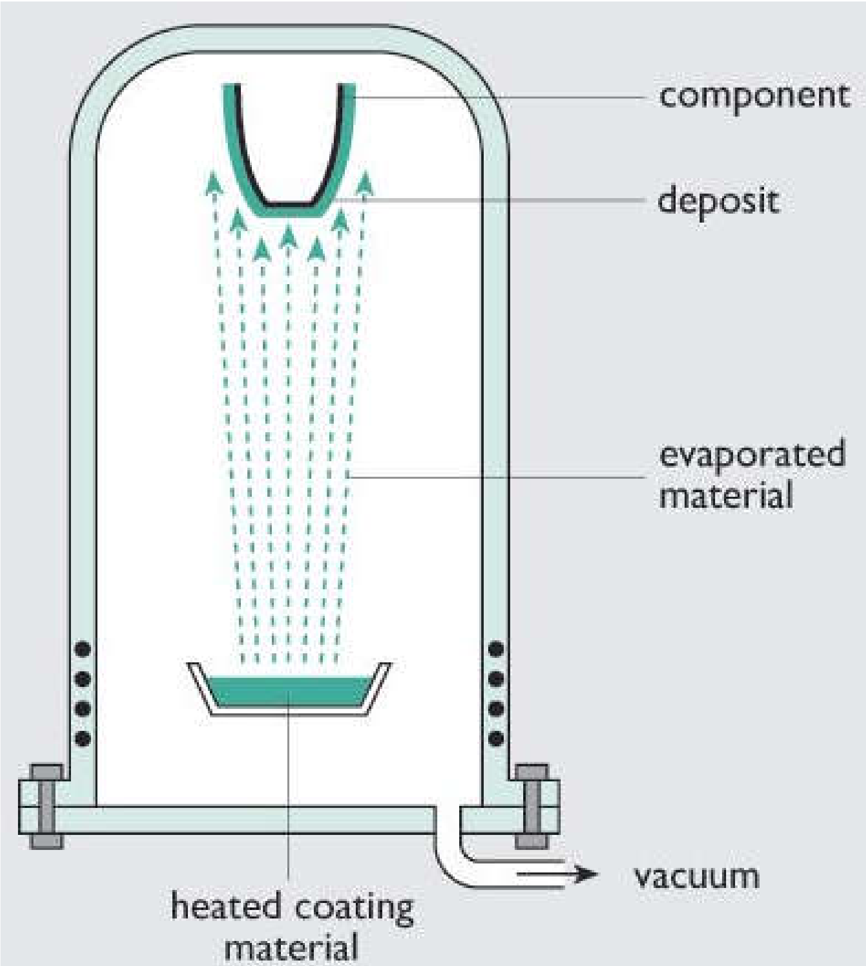
PVD vs. CVD

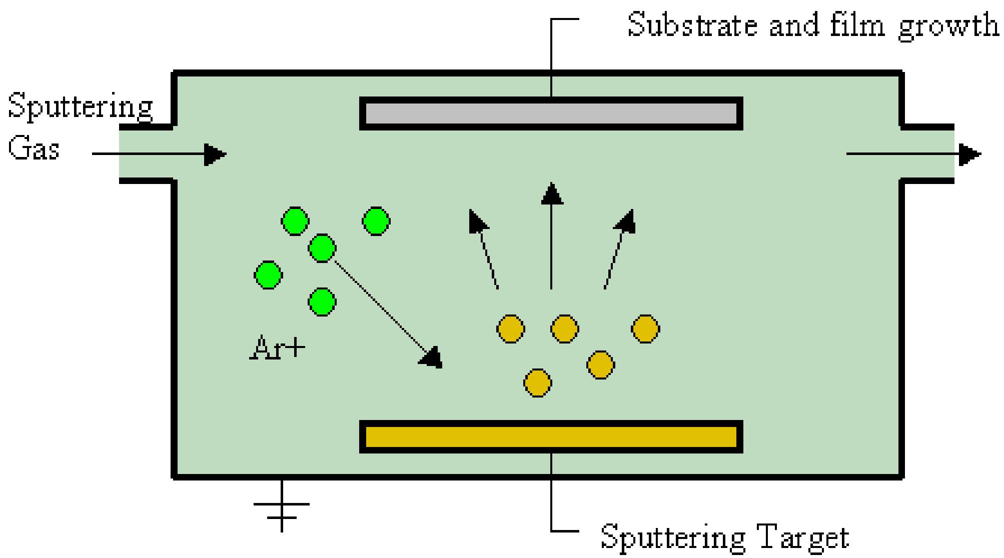
Physical process | **Chemical reactions**





PVD





Evaporation (蒸发)

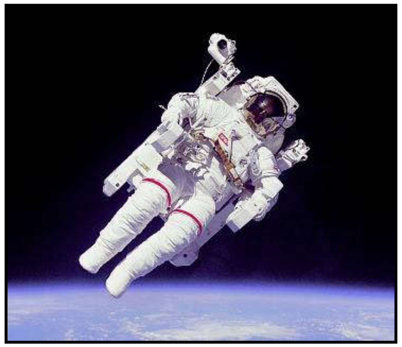
Sputter (溅射)

Vacuum Basics

- Units
  - 1 Pa = 1 N/m^2
  - 1 atm = 760 torr = 760 mm Hg = 1.013*10^5 Pa
  - 1 bar = 10^5 Pa = 750 torr
  - 1 torr = 133.3 Pa

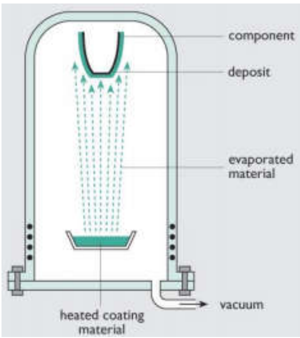
Pressure cooker

~ 1.5 atm



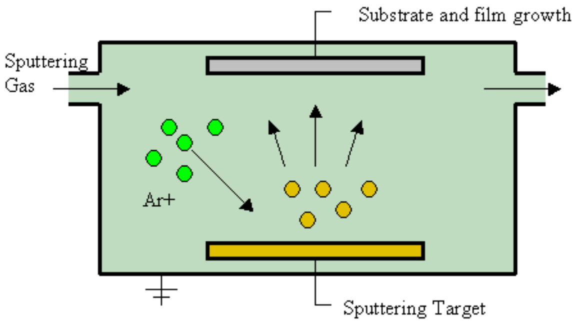
outer space

< 10^{-10} Pa



Evaporation

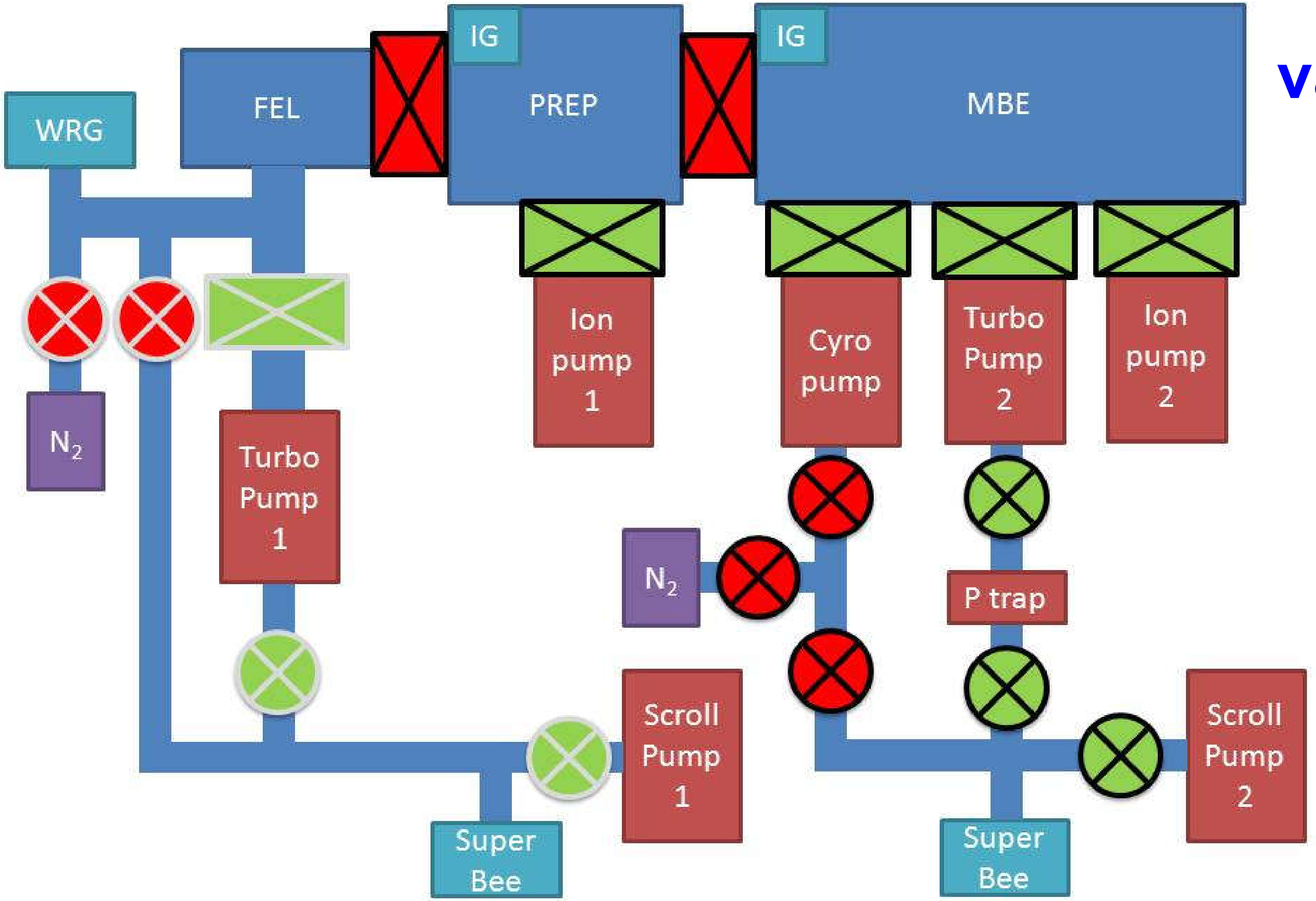
< 10^{-7} Pa



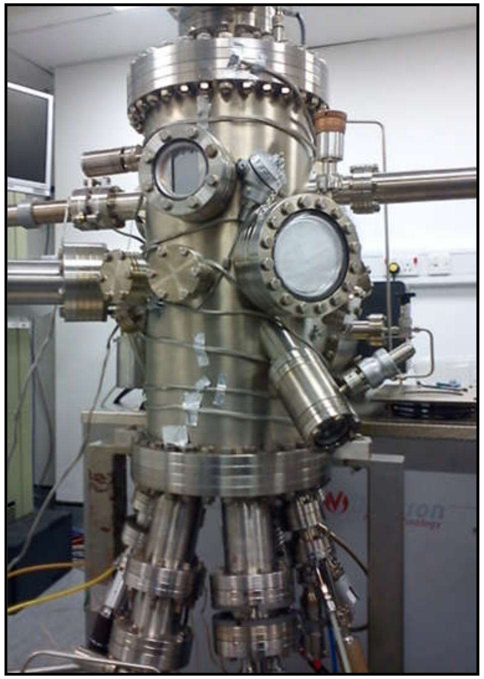
Sputter

~ 10^{-1} Pa

Vacuum Systems



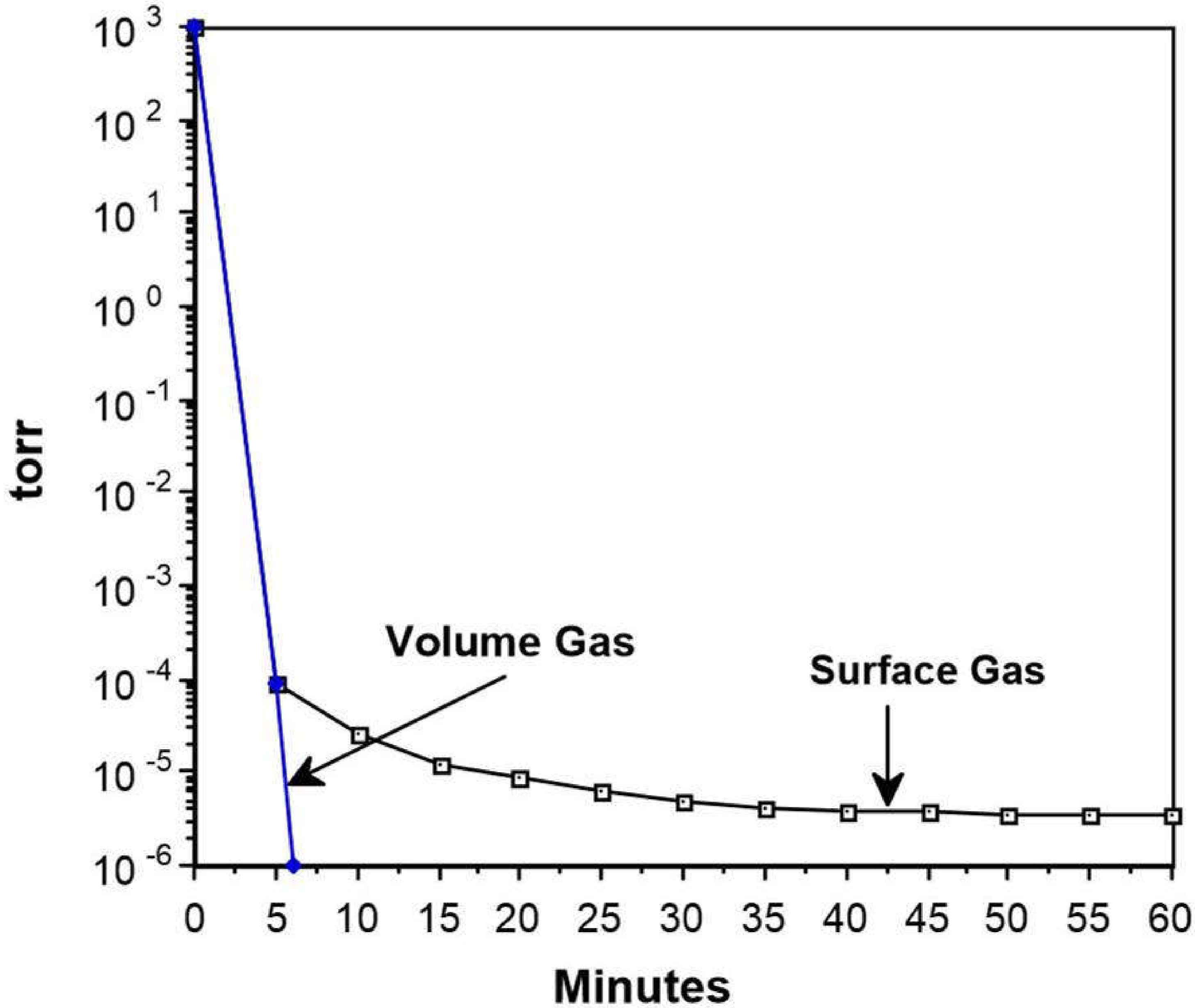
vacuum ~ 10^{-10} Pa



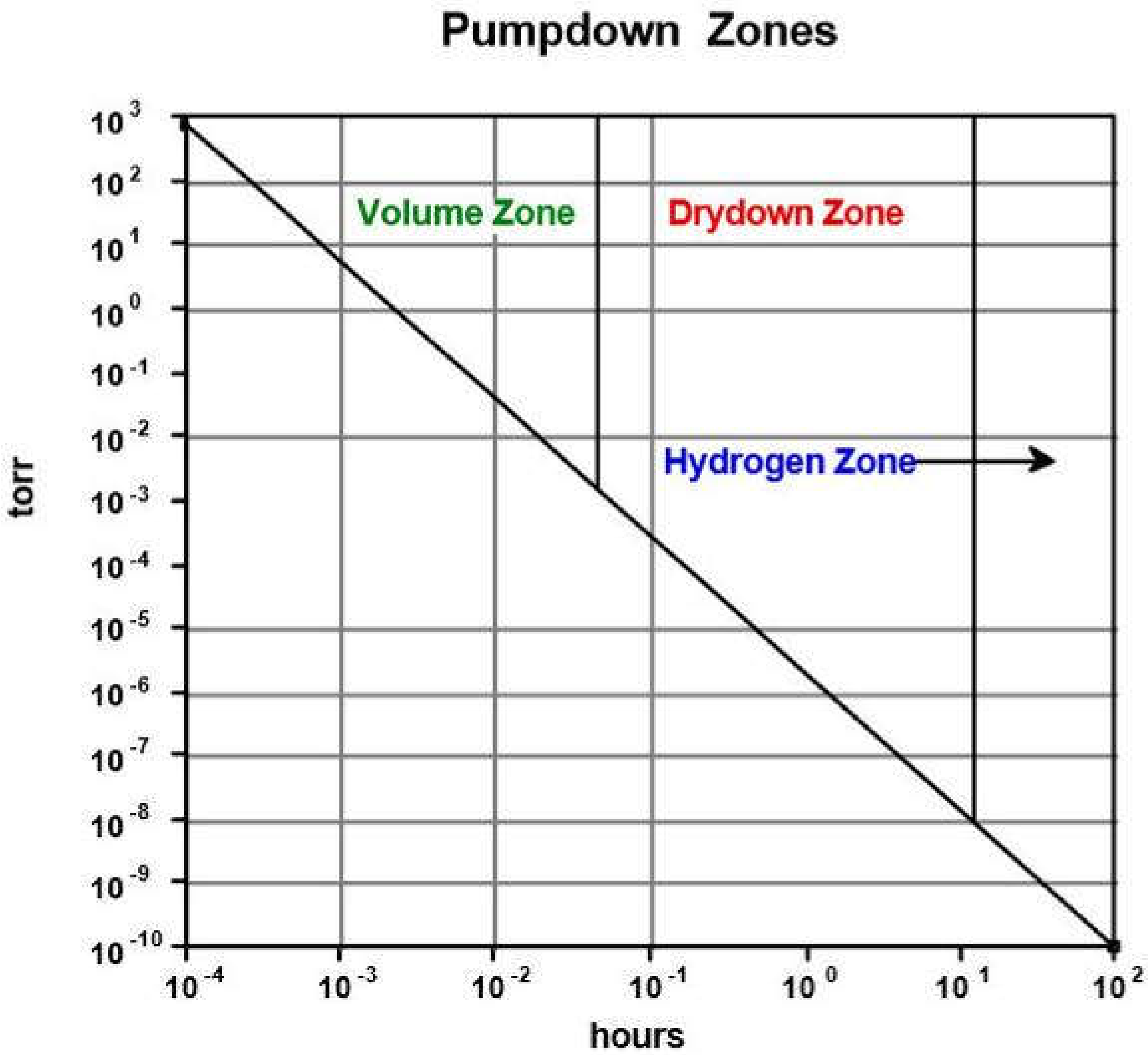
MBE: Molecular Beam Epitaxy

分子束外延

Vacuum Pumpdown

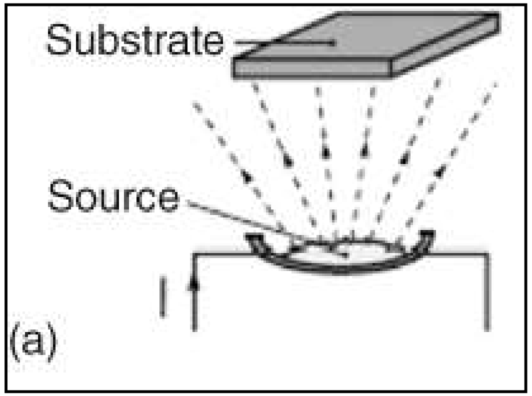


Vacuum Pumpdown

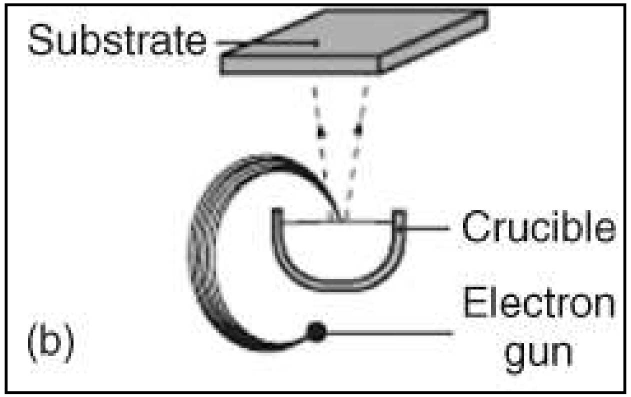


1. air
2. water
3. hydrogen

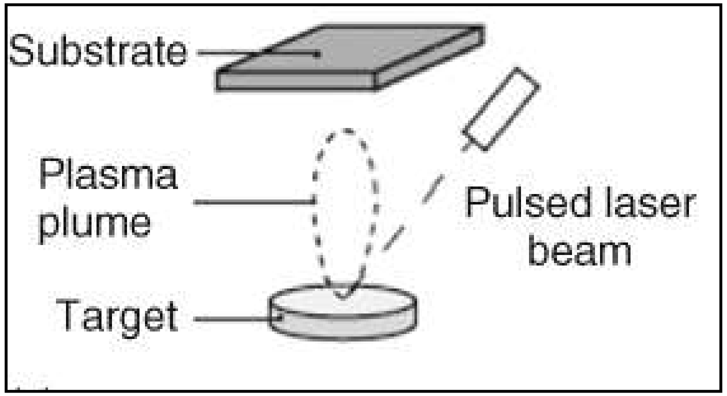
Evaporation



Thermal



Electron Beam (Ebeam)



Pulsed Laser Deposition (PLD)

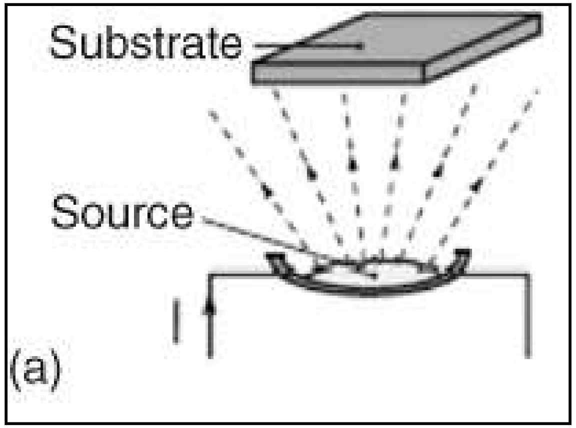
Q: Why do we need the vacuum?

Evaporation

- Reduce the impurities (N_2, O_2, H_2O, ...)

- Prevent oxidation
  - e.g. $Cu + O_2 \rightarrow CuO$

- Ballistic transport
  - molecular mean free path λ



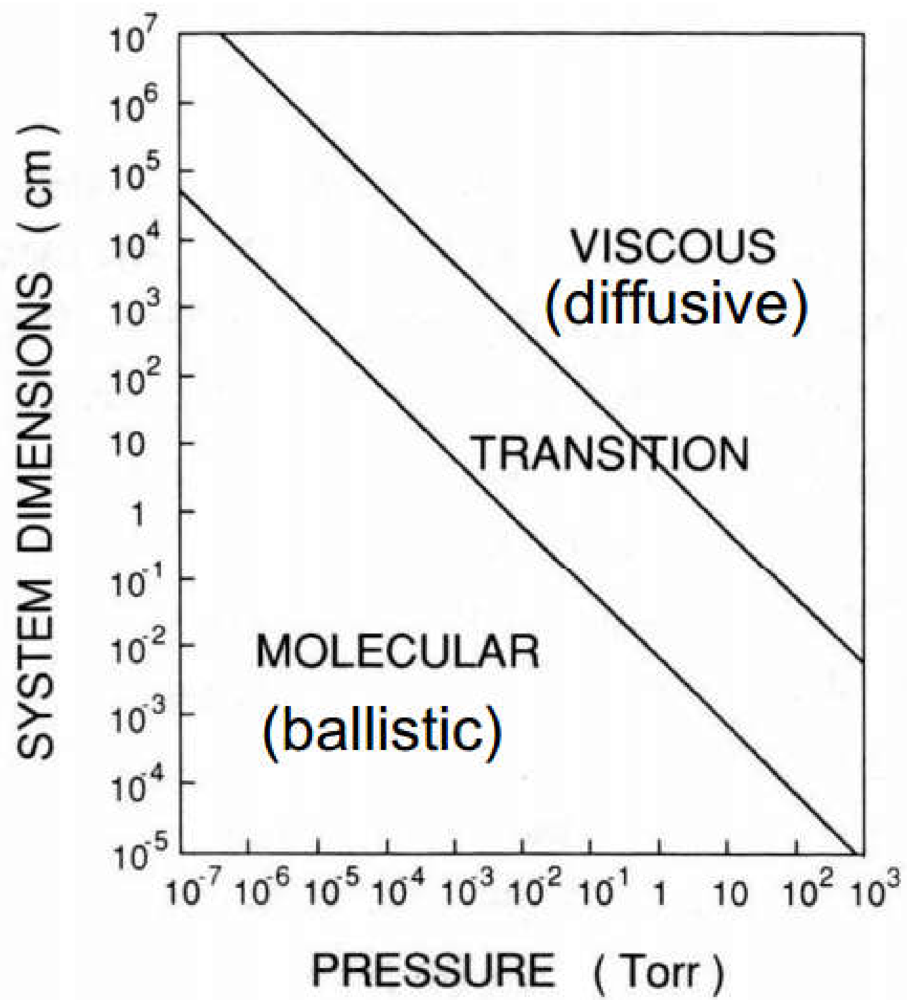
$$\lambda = \frac{kT}{\sqrt{2}\pi r^2 p}$$

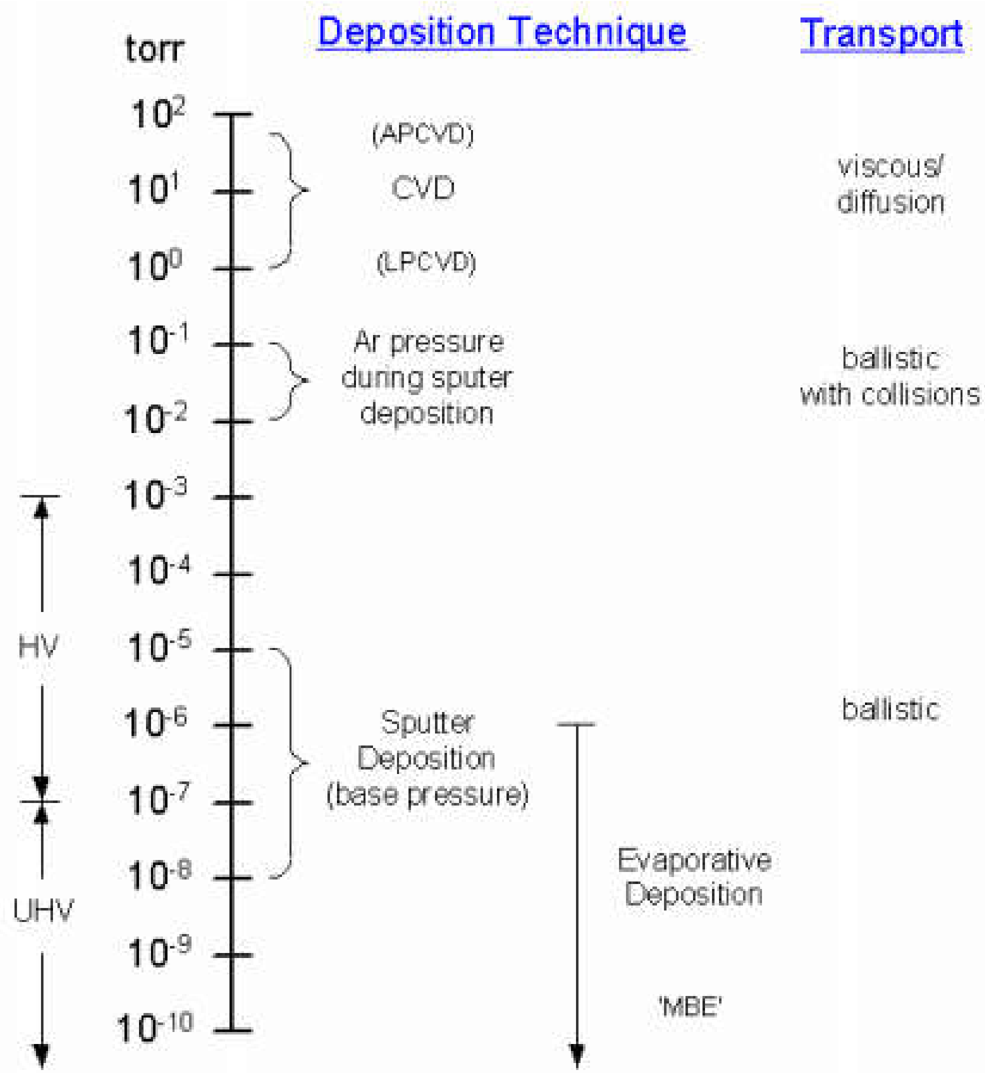
$$\lambda\,(\mathrm{cm}) \approx \frac{0.5}{pressure\,(\mathrm{Pa})}$$

Q: Required pressure?

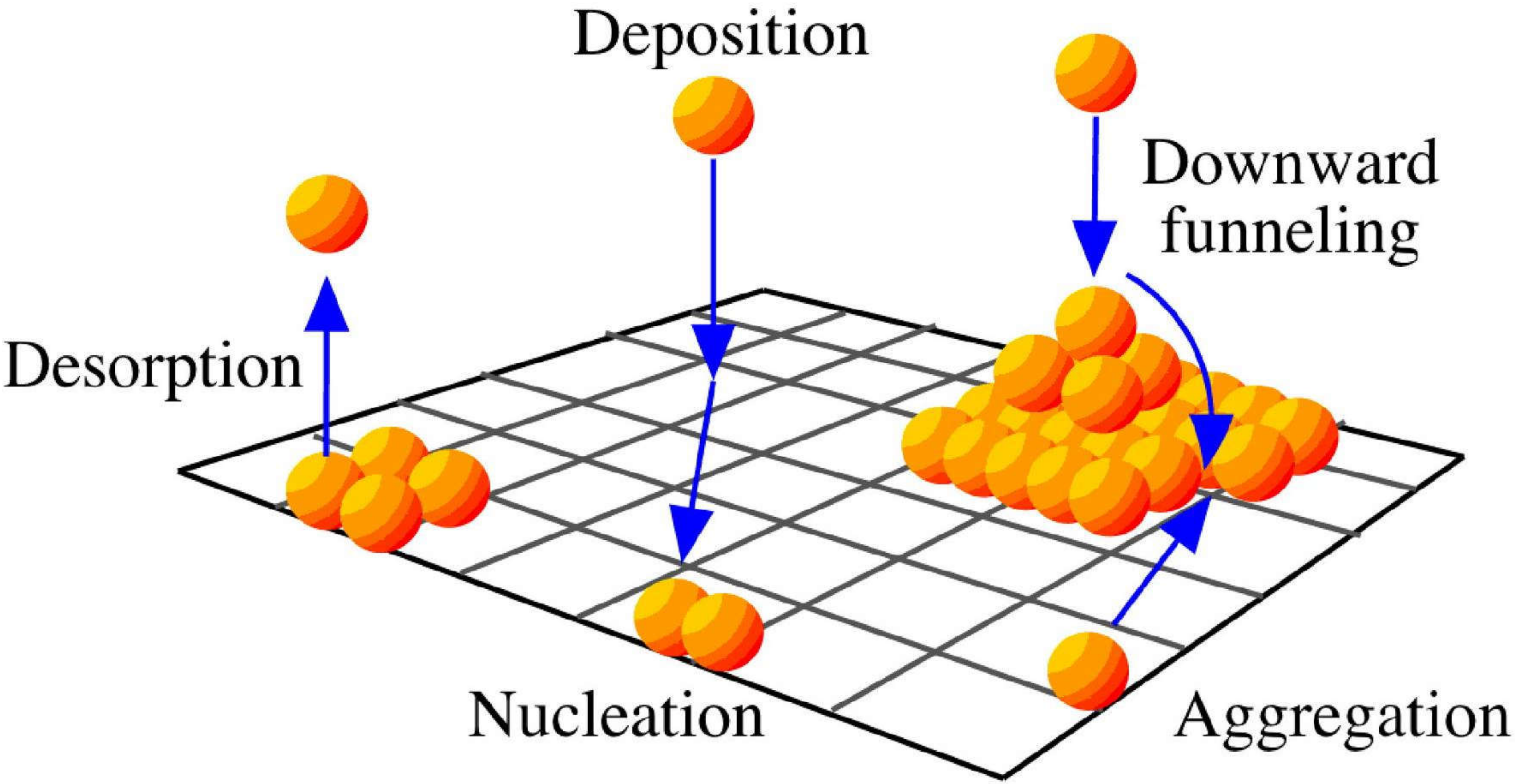
Mass Transport

$$\lambda\,(\text{cm}) \approx \frac{0.5}{pressure\,(\text{Pa})}$$





Mass Transport

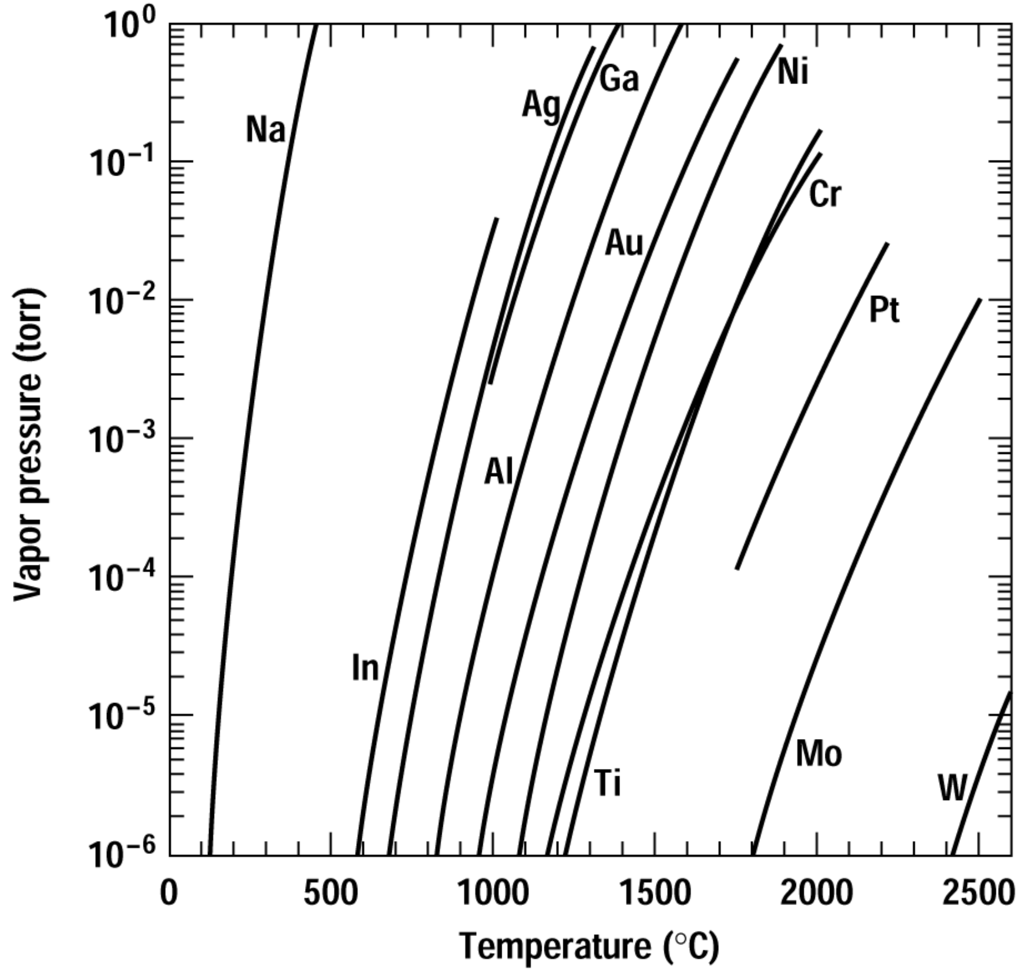


absorption - movement - desorption

Evaporation Rate

Langmuir-Knudsen Theory

$$R_{evap} = 5.83\times10^{-2} A_s \sqrt{\frac{m}{T}} P_e$$



R_{evap}: Evaporation rate (g/s)

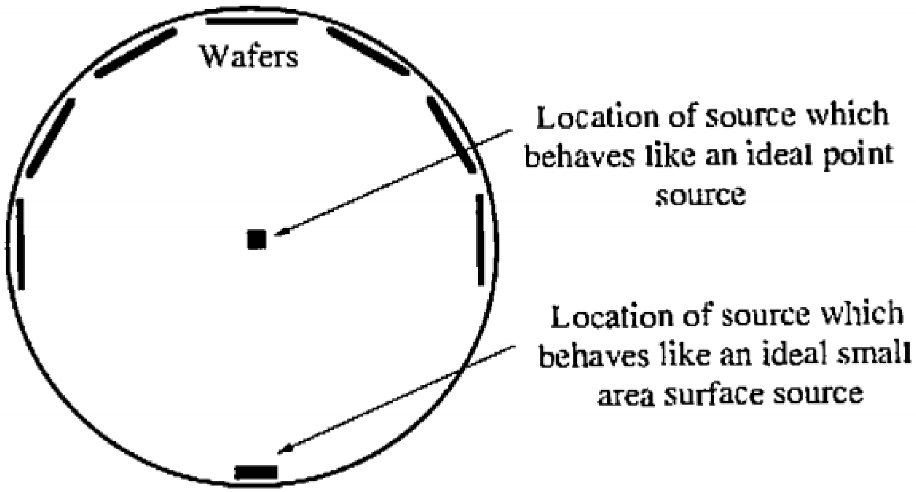
A_s: area of sources (cm^2)

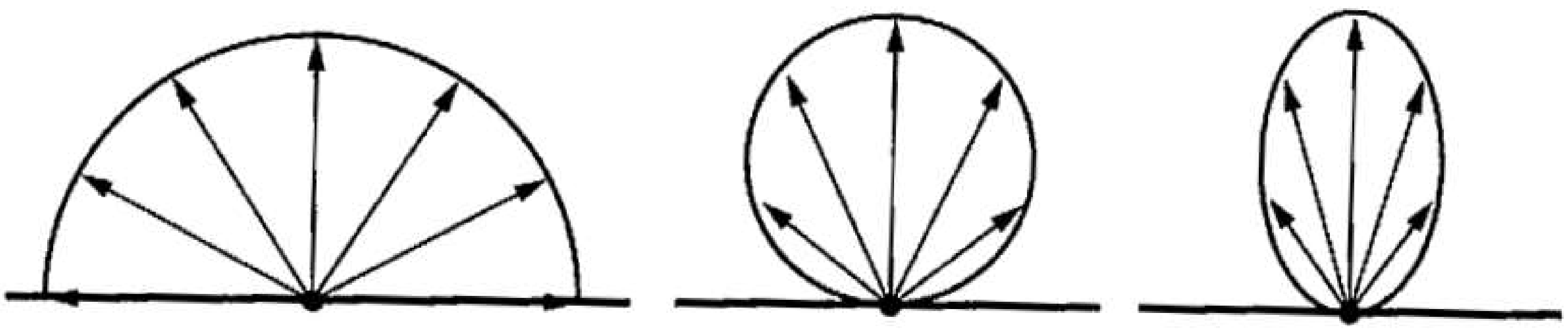
m: molecular weight (g/mol)

T: temperature (K)

P_e: vapor pressure of sources (Torr) (*not* chamber pressure)

Evaporation Sources





(a) Uniform (isotropic) emission from a point source

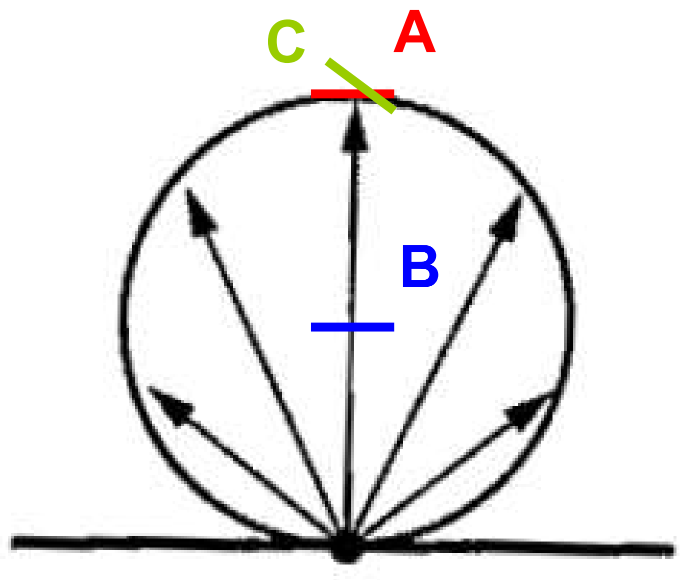
(b) Ideal cosine emission from a small planar surface source. ($n = 1$ in $\cos^n\theta$ distribution)

(c) Non-ideal, more anisotropic emission from a small planar surface source. ($n > 1$ in $\cos^n\theta$ distribution)

Deposition rate

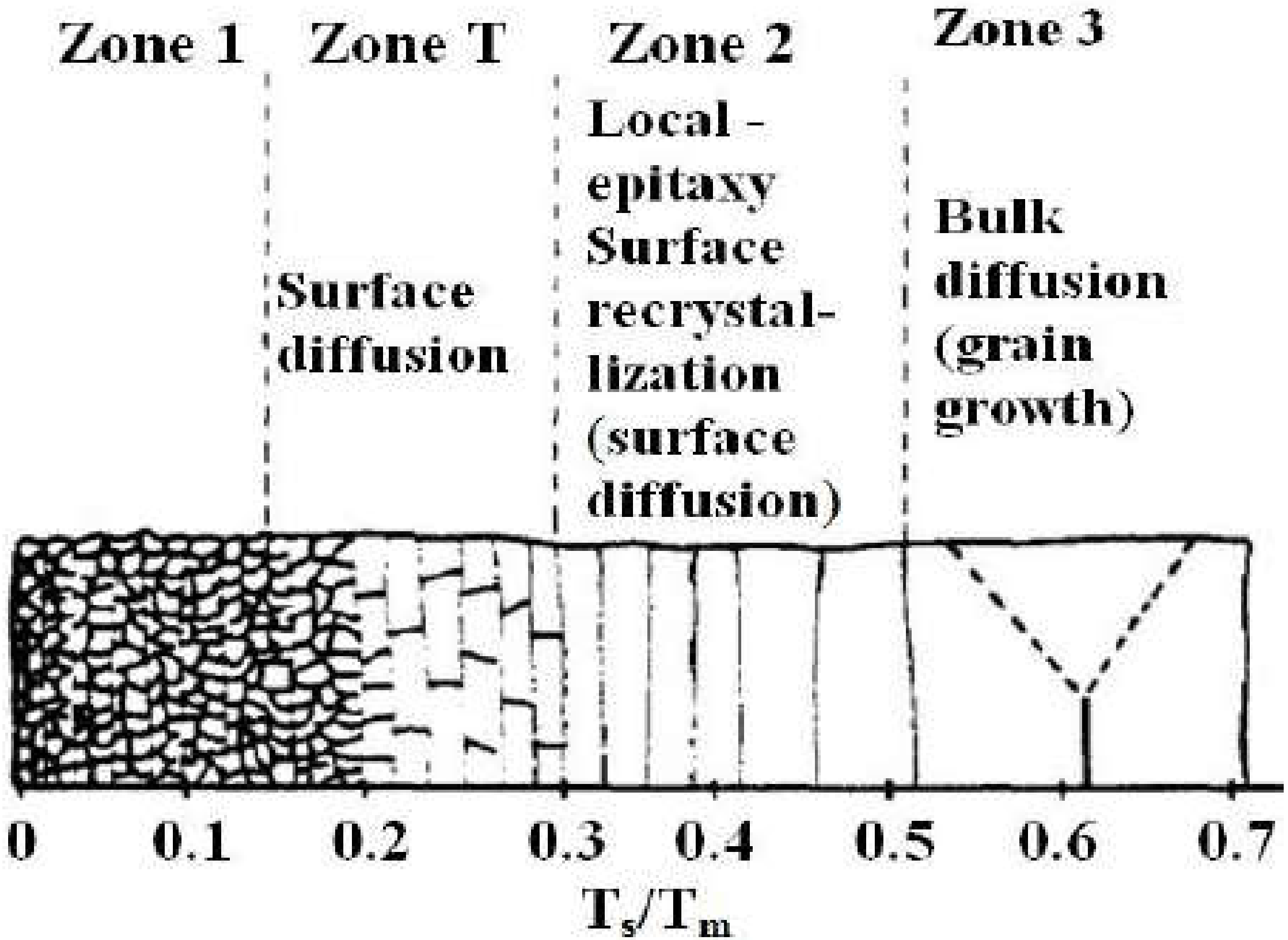
Question:

1. $R_A : R_B = ?$
2. $R_A : R_C = ?$



Ideal cosine emission from a small planar surface source.

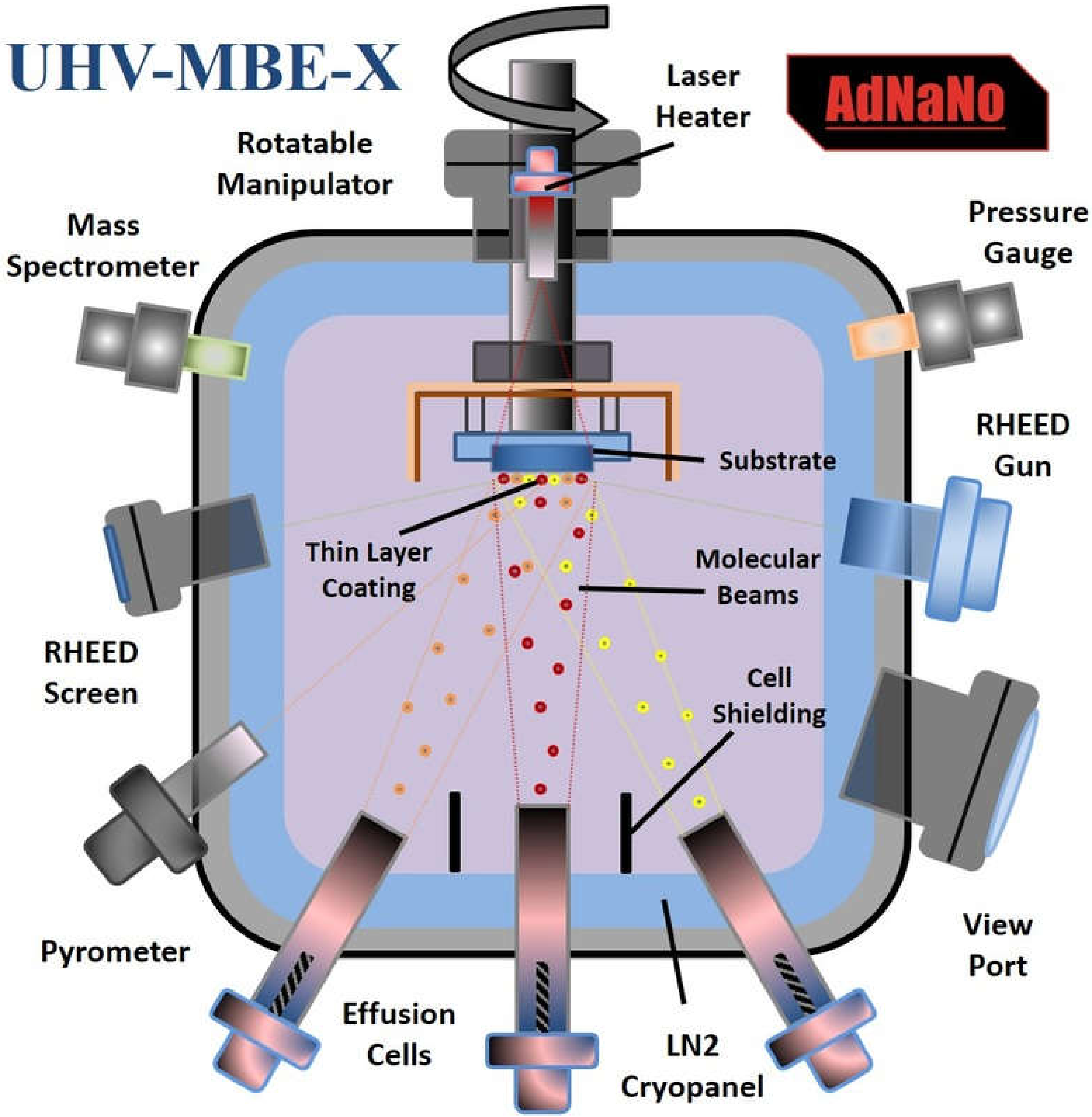
Effects of Substrate Temperature



Zone Model

Higher Temperature
-> Larger Atom Mobility
-> Larger Grain Size

MBE: Molecular Beam Epitaxy

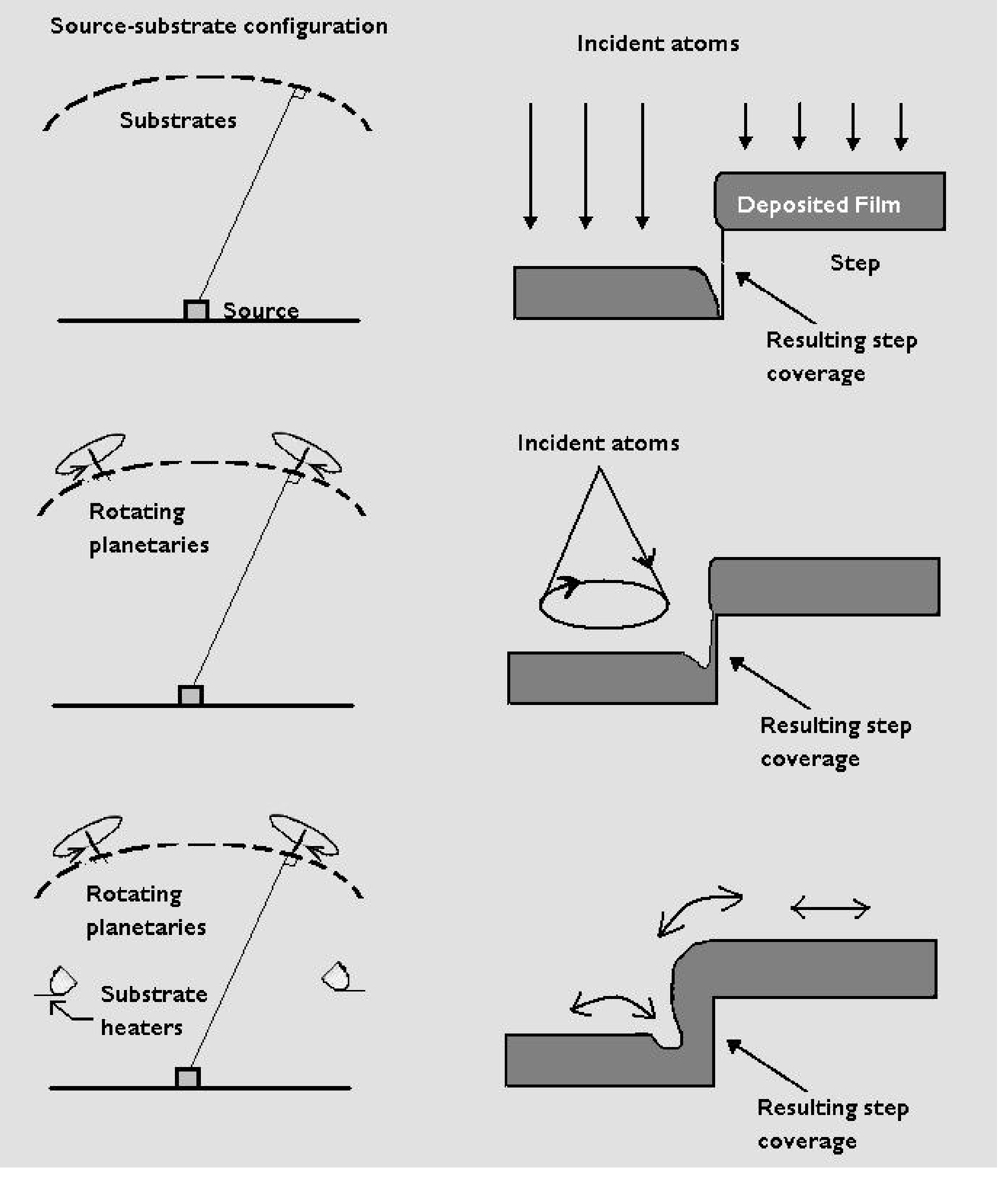


Ultrahigh Vacuum
High Substrate Temperature
Lattice Matched Substrate

↓

High Quality,
Single Crystal Films

Step Coverage



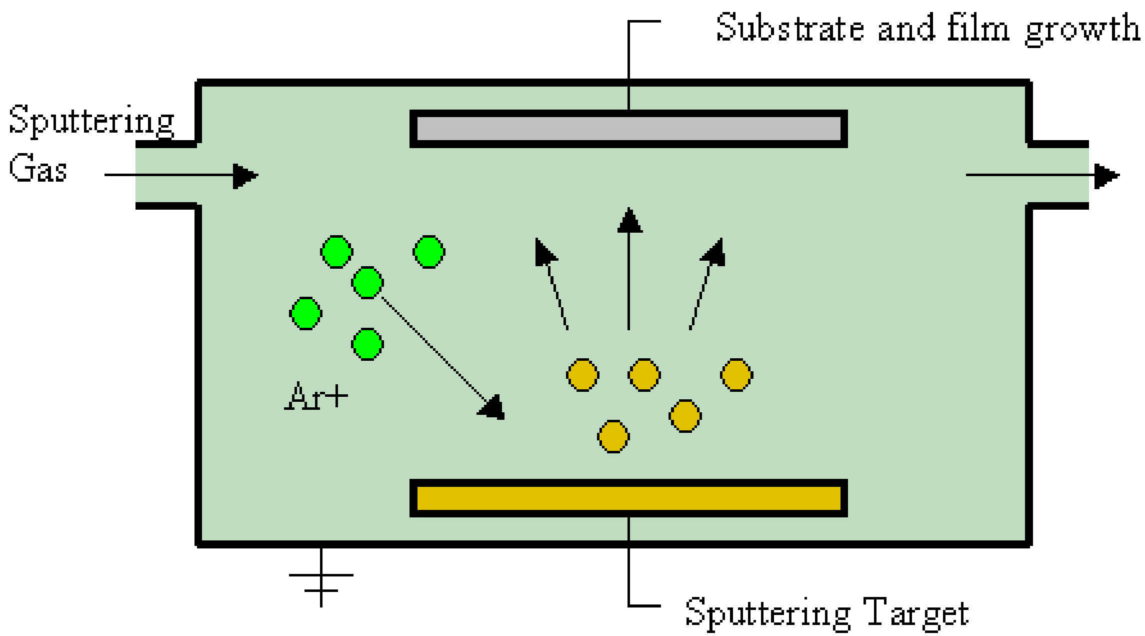
Substrate rotation and heating improve step coverage

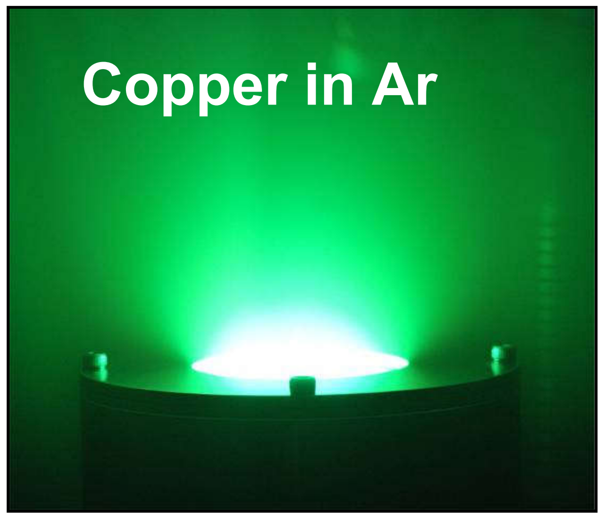
Challenges of Evaporation

- Materials with high melting points / low vapor pressure
  - W, Mo, SiO_2, ...
- Compounds and alloys (non-stoichiometry)
  - FeCoB alloy
  - TiO_2 -> TiO_x
- Radiation damage generated by Ebeam
  - electron beam and X-ray radiation
- Poor step coverage
  - via filling

Sputter (溅射)

- **Plasma (e.g. Ar) assisted transport**
  - **high energy**
  - **high deposition rate**

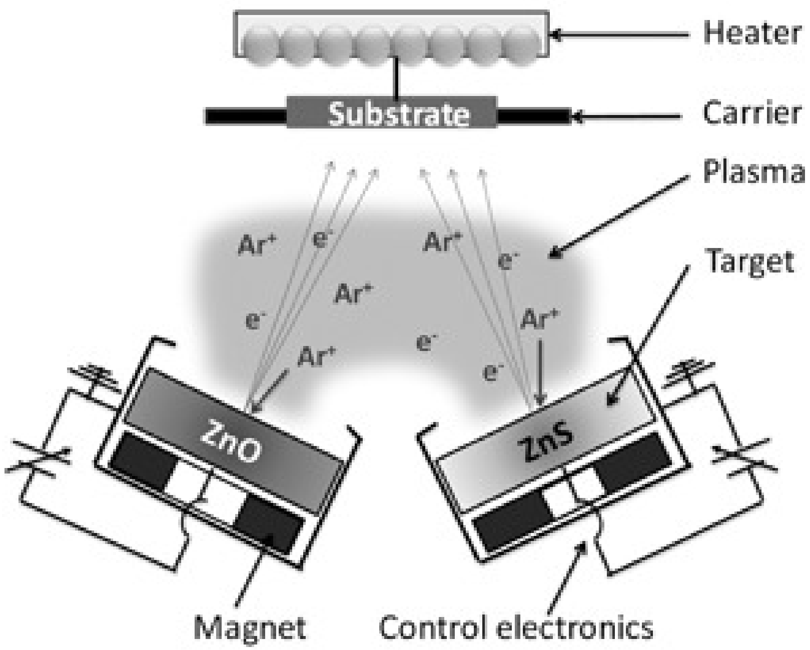


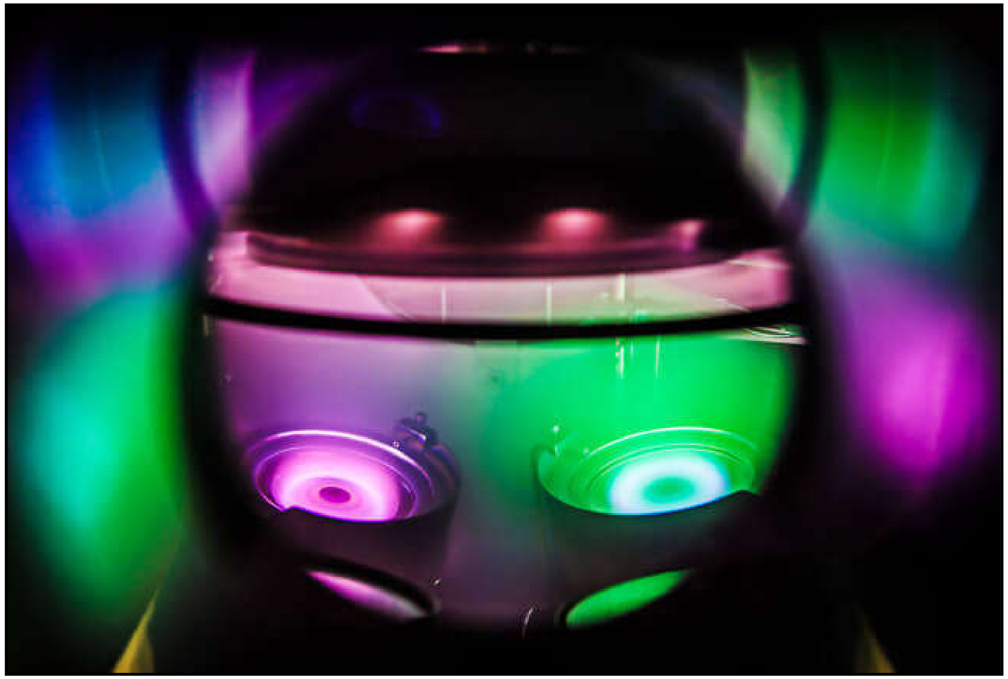


Plasma

Co-Sputter

- **Deposit more than one material**
  - **composition control**





Sputter: Pros. & Cons.

- Advantages
  - Higher pressure than evaporation
  - Higher deposition rate
  - Better uniformity and step coverage
  - Better stoichiometry control
  - Work for most materials

- Disadvantages
  - Plasma induced damages (etching)
  - More impurities and defects
  - Not good for single crystal epitaxy
  - Mostly polycrystalline and amorphous films

Sputter

- **Process Parameters**
  - Type: DC, RF/AC, Magnetron, ...
  - Substrate temperature
  - Gas type (Ar, O_2, N_2, ...)
  - Chamber pressure
  - Sputter power
  - ...

- **Control Parameters**
  - Deposition rate
  - Crystallinity
  - Film quality (defects, ...)
  - ...

Sputter

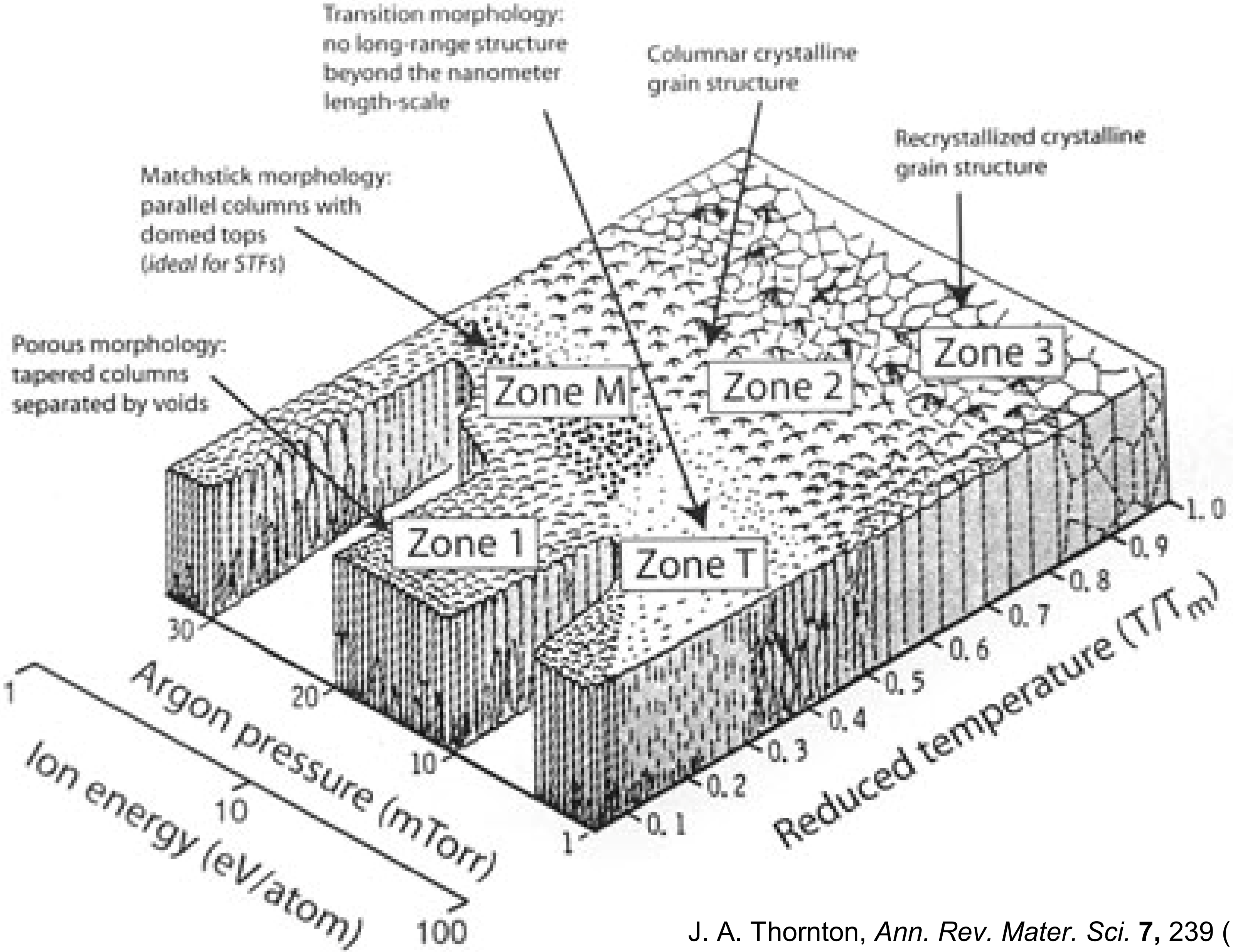
Sputtering Process Trend for typical metals and films

	Base Pressure	Sputtering Pressure	Power	Substrate RF Bias
Deposition Rate	⇔	⇧ | ⇩ Below~3mT Above~8mT	⬆	⇩
Stress (+ tensile, - compressive)	⇔	⬆	⬇	⬇
Step Coverage/ Sidewall coverage	⇔	⇧	2nd order effect depending on geometry	⇧ Can cause re-dep onto sidewalls thru collisions
Resistivity	⬆	⇧	2nd order effect with substrate or target heating on some films	2nd order effect with some films by changing density or stress

Legend

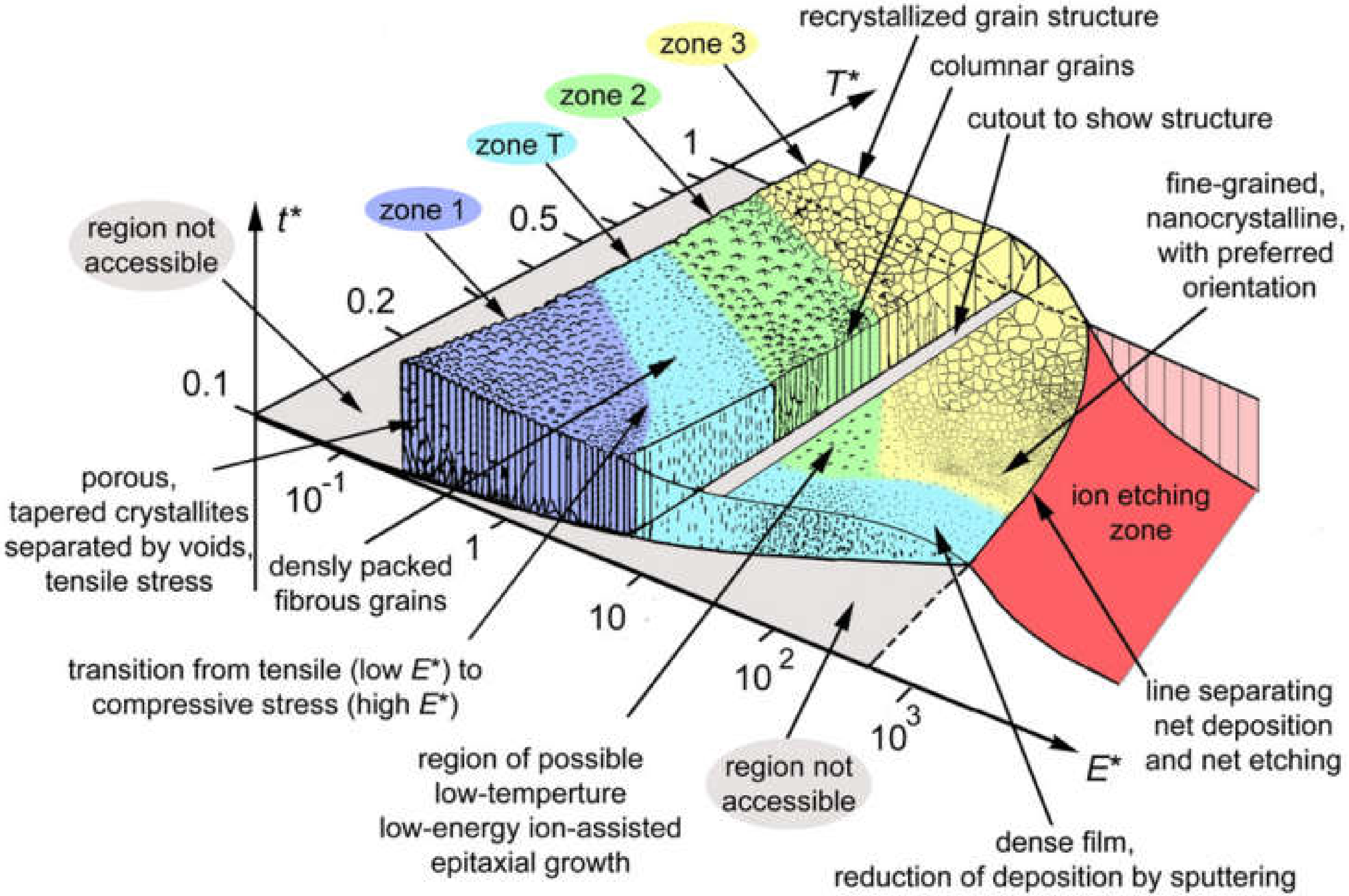
⬆	Strong increase in response	⇧	Slight increase in response	⇔	Typically no response
⬇	Strong decrease in response	⇩	Slight decrease in response		

Thornton's Zone Model



J. A. Thornton, *Ann. Rev. Mater. Sci.* **7,** 239 (1977)

Refined Zone Model

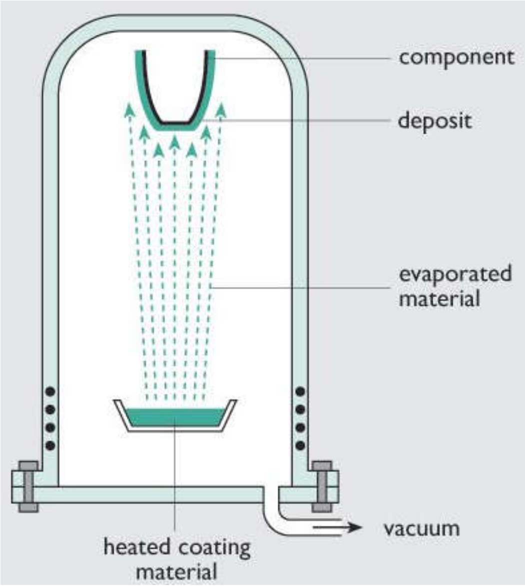


A. Anders, *Thin Solid Films* **518,** 4087 (2010)

Evaporation vs. Sputter

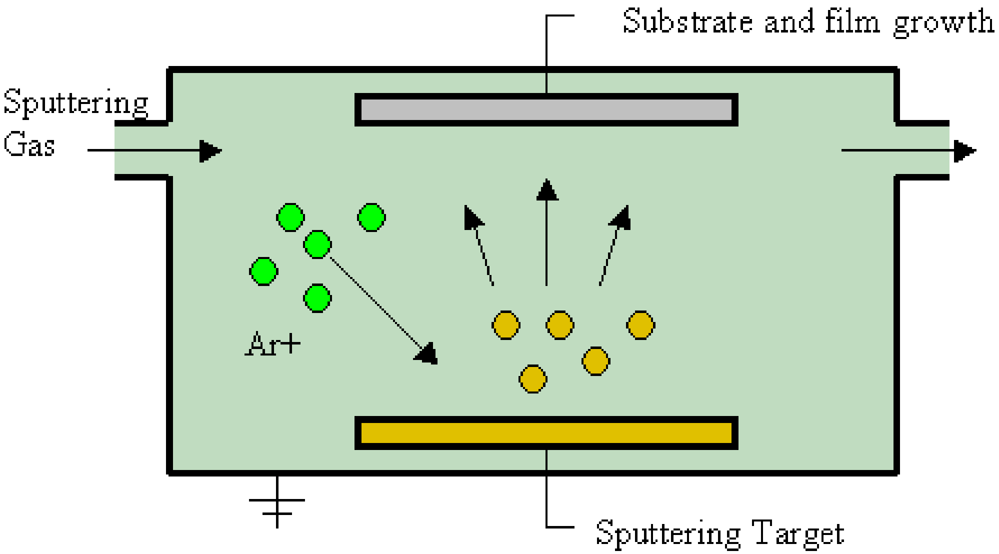
Evaporation:

- higher temperature
- radiation (Ebeam)
- lower pressure
- poor step coverage

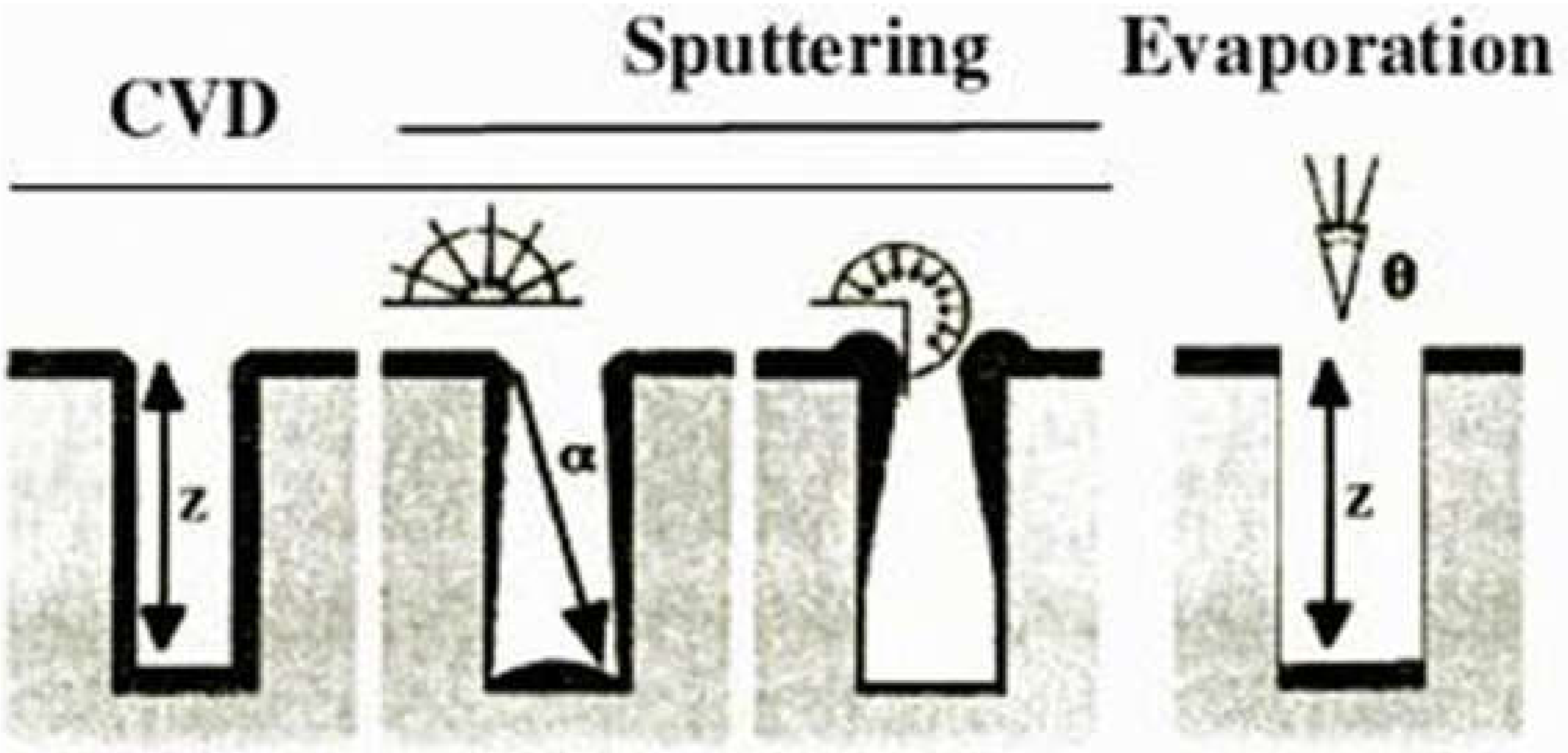


Sputter:

- lower temperature
- plasma damage
- higher pressure
- better step coverage



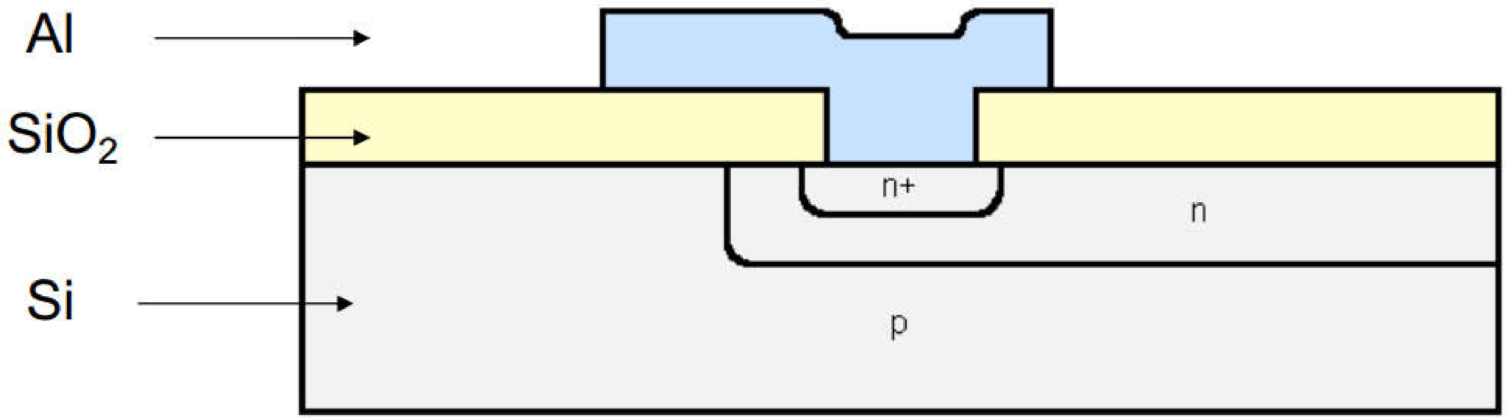
Step Coverage



surface reaction → *ballistic transport*

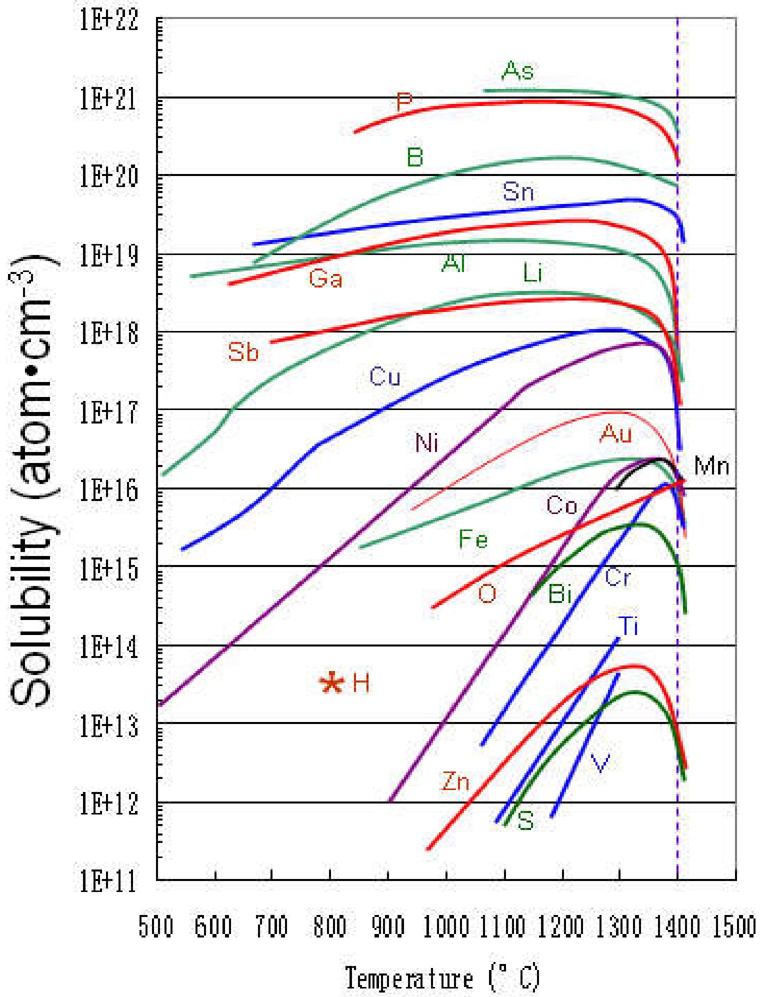
Film Adhesion

- **Al has good adhesion on Si and SiO_2**
  - **Al has high solubility in Si**
  - **$Al + SiO_2 = Al_2O_3 + Si$**



Q: How about Cu and Au?

Film Adhesion

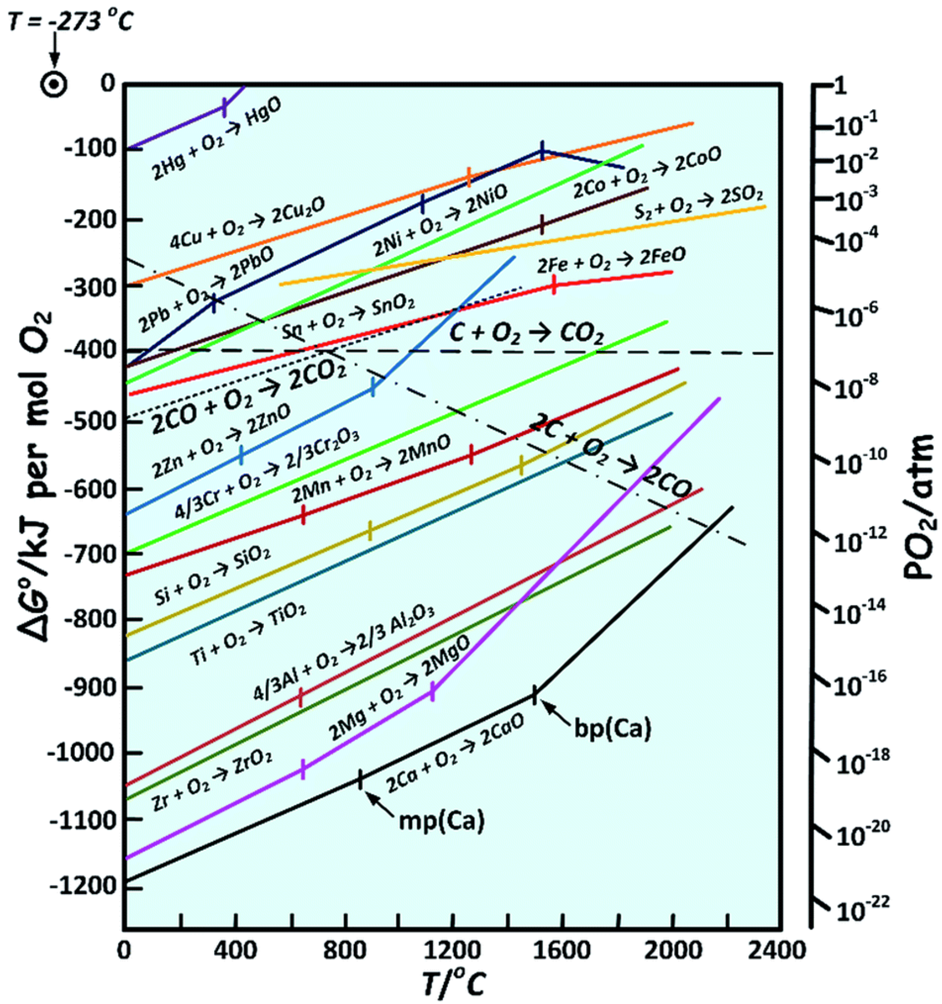


solubility of metals in Si

Film Adhesion

Ellingham diagram

Formation of metal oxides

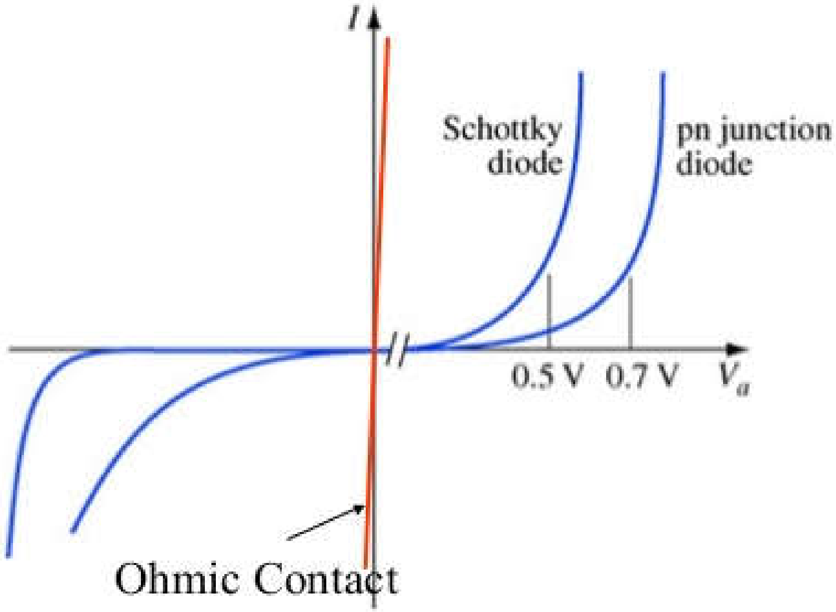


Film Adhesion

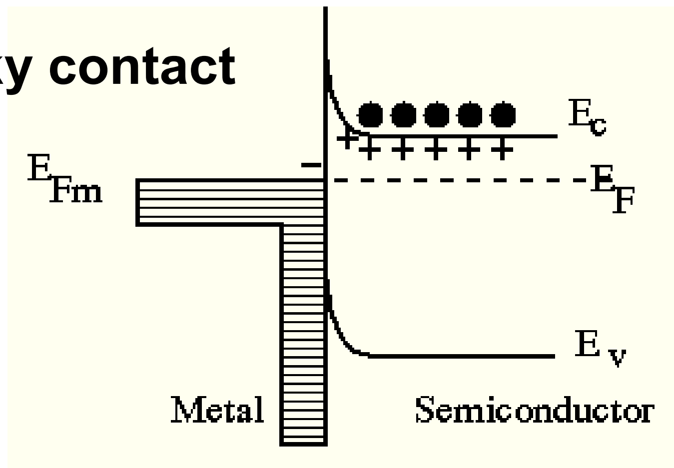
- Metals like Ag and Au tend to have poor adhesion on Si and SiO_2
- Substrate clean
- Deposit a thin (~5 nm) Ti or Cr layer for adhesion
- Plasma treatment
- Monolayer bonding
- ...

Typical Ohmic Contacts for III-V

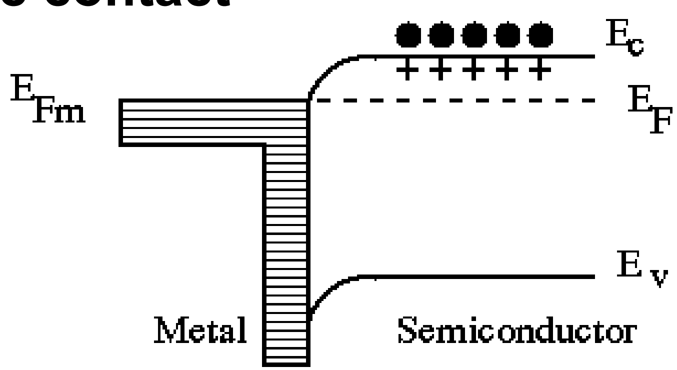
- **GaAs**
  - p-GaAs Be/Au, Ti/Pt/Au, ...
  - n-GaAs Ge/Ni/Au, Pd/Ge, ...
- **GaN**
  - p-GaN Ni/Au
  - n-GaN Ti/Al/Au



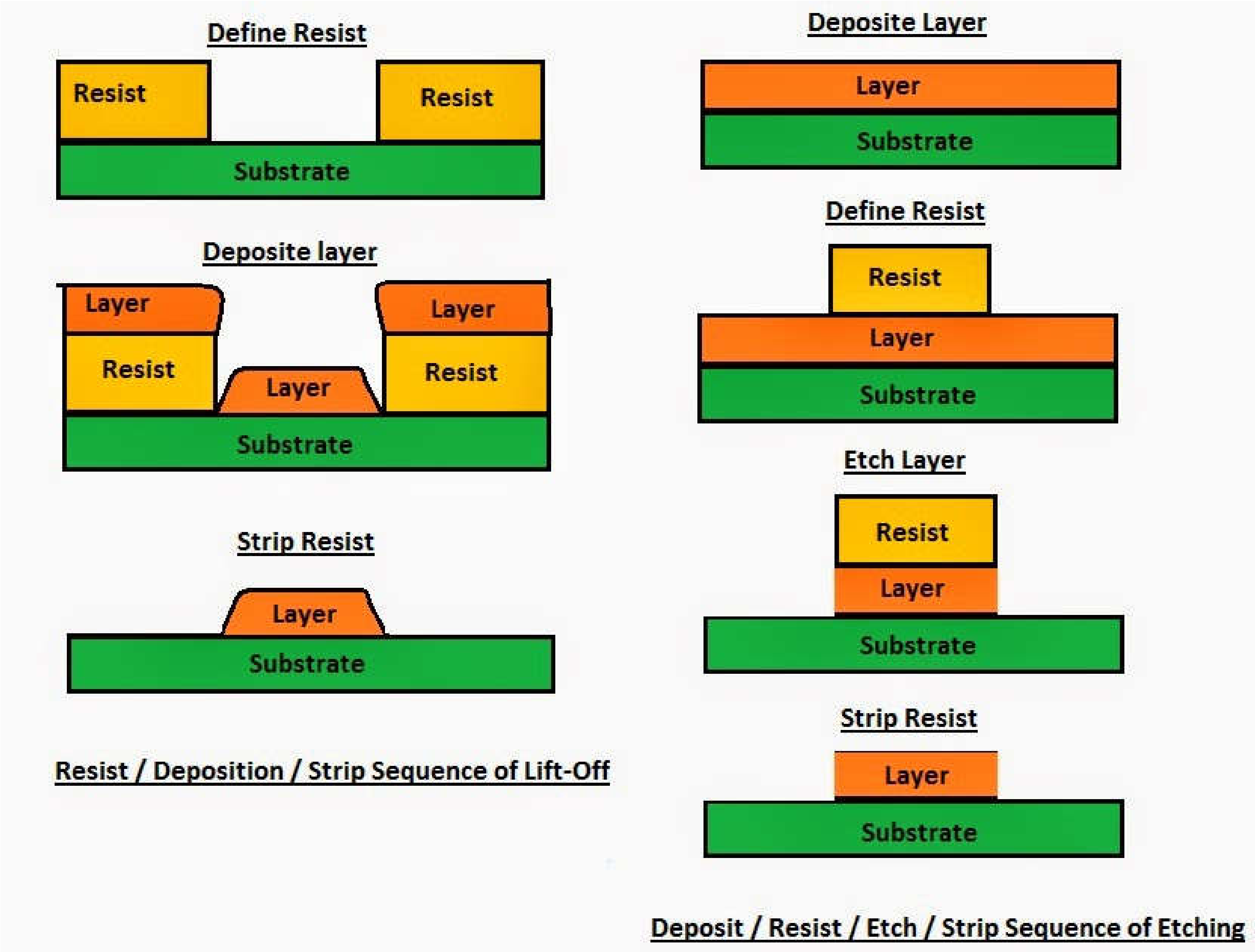
Schottky contact



Ohmic contact

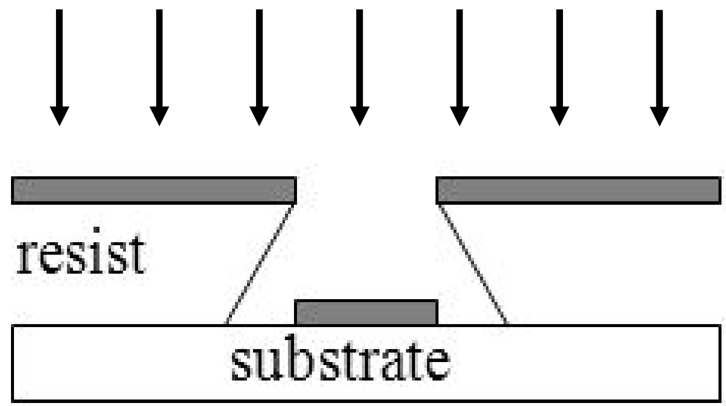


Thin Film Patterning

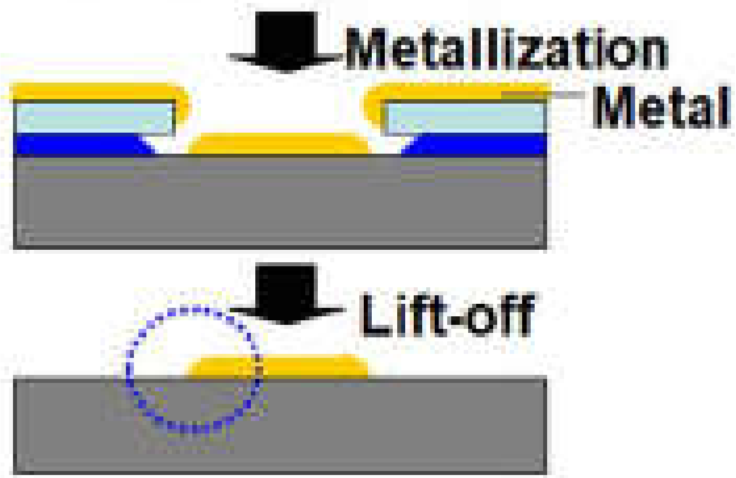


Requirements for Liftoff

- **Avoid Step Coverage**

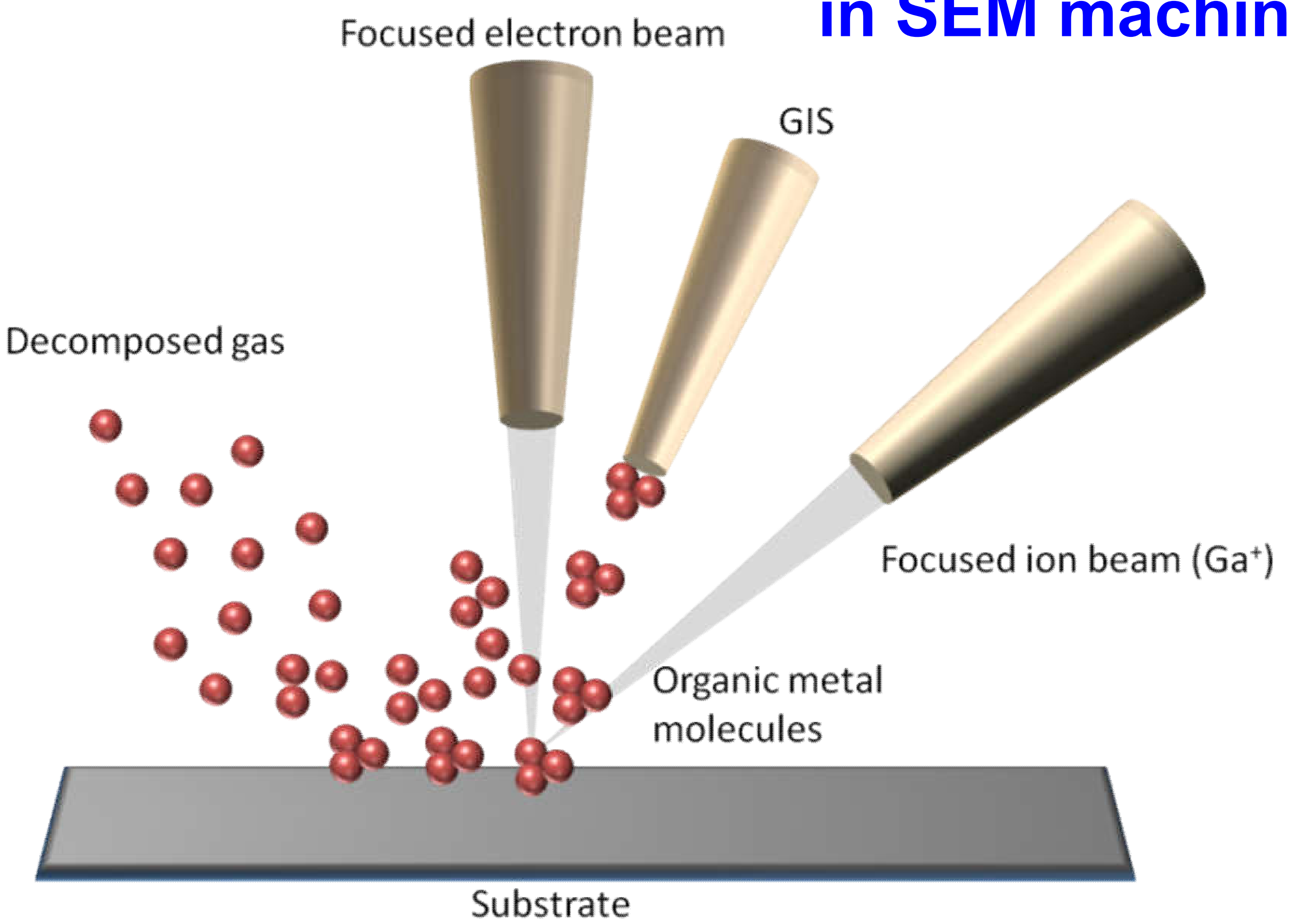


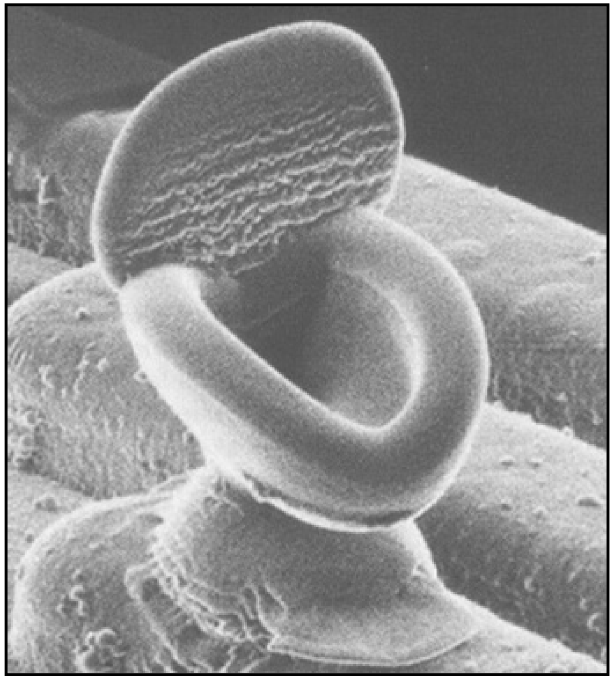
- **PVD instead of CVD**
  - **avoid high temperature**
- **Photoresist (PR) process**
  - **negative PR preferred (*Why?*)**
  - **increase PR thickness**
  - **multilayer PR**



Focused Ion Beam (FIB) Deposition

in SEM machine





world's smallest toilet

Etch: Ga
Deposition: Pt